

ABSTRACT OF THE DISCLOSURE

There are provided a method and apparatus for forming interconnects by embedding a metal such as copper (Cu) into recesses for interconnects formed on the surface of a substrate such as a semiconductor substrate. The method of the present invention includes the steps of: providing a substrate having fine recesses formed in the surface; subjecting the surface of the substrate to plating in a plating liquid; and subjecting the plated film formed on the surface of the substrate to electrolytic etching in an etching liquid.

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